



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20260501000.0
Datasheet for INA12x, INA2128, INA141, and INA117
Information Only**

Date: May 04, 2026

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team.

Sincerely,

Change Management Team
SC Business Services

20260501000.0
Information Only Datasheet
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
INA129UA/2K5	
INA117SM	
INA128U	
INA141U	
INA128U/2K5	
INA141UA	
INA117KU	
INA128UA	
INA141UA/2K5	
INA129U/2K5	
INA2128UA	
INA117SM	
INA2128U	
INA129P	
INA117SMQ	
INA128PA	
INA129U/2K5	
INA2128U	
INA117KU/2K5	
INA128U	
INA128UA/2K5	
INA141U/2K5	
INA117P	
INA117AM	
INA117KU	
INA129UA	
INA117BM	
INA128P	
INA128PA	
INA129PA	
INA2128U/1K	
INA141UA/2K5	
INA2128UA/1K	
INA129U	

Technical details of this Product Change follow on the next page(s).

Notification Number:	20260501000.0	Notification Date:	May 04, 2026
Title:	Datasheet for INA12x, INA2128, INA141 and INA117		
Customer Contact:	Change Management team	Dept:	Quality Services
Change Type:	Electrical Specification		

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



INA128, INA129

SBOS051G – OCTOBER 1995 – REVISED JANUARY 2026

Changes from Revision F (May 2022) to Revision G (January 2026)

Page

• Added different fabrication process specifications for Input bias current in the <i>Features</i> section.....	1
• Added description of device flow information in the <i>Specifications</i>	4
• Added all chips site origins (CSO) condition to the typical test conditions in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Offset voltage (RTI) in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Power-supply rejection ratio (RTI) in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Long-term stability in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Common-mode rejection ratio in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Input bias current in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Input offset current in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Voltage noise (RTI) in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Current noise in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Gain error in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Gain drift in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Positive output voltage swing in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Negative output voltage swing in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Short-circuit current in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Bandwidth, –3dB in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Slew rate in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Settling time in the <i>Electrical Characteristics</i>	5
• Added all <i>chips site origins</i> (CSO) condition to the typical test conditions in the <i>Typical Characteristics</i>	9
• Added CSO: SHE to <i>Common-Mode Rejection vs Frequency</i> , <i>Positive Power Supply Rejection vs Frequency</i> , <i>Input-Referred Noise vs Frequency</i> , <i>Settling Time vs Gain</i> , <i>Input Bias Current vs Temperature</i> , <i>Output Voltage Swing vs Output Current</i> , <i>Output Voltage Swing vs Power Supply Voltage</i> , <i>Short Circuit Output Current vs Temperature</i> , and <i>Small Signal</i> curves in the <i>Typical Characteristics</i>	9

• Added CSO: FRE to <i>Gain vs Frequency</i> , <i>Negative Power Supply Rejection vs Frequency</i> , <i>Input Overvoltage V/I Characteristics</i> , <i>Maximum Output Voltage vs Frequency</i> , <i>Total Harmonic Distortion + Noise vs Frequency</i> , and <i>Large Signal</i> curves in the <i>Typical Characteristics</i>	9
• Added <i>Gain vs Frequency</i> , <i>Input-Referred Noise vs Frequency</i> , <i>Positive Power Supply Rejection vs Frequency</i> , <i>Negative Power Supply Rejection vs Frequency</i> , <i>Input Overvoltage V/I Characteristics</i> , <i>Maximum Output Voltage vs Frequency</i> , <i>Total Harmonic Distortion + Noise vs Frequency</i> , and <i>Large Signal</i> curves for CSO: SHE in the <i>Typical Characteristics</i>	9
• Added <i>Common-Mode Rejection vs Frequency</i> , <i>Positive Power Supply Rejection vs Frequency</i> , <i>Input-Referred Voltage Noise vs Frequency</i> , <i>Input-Referred Current Noise vs Frequency</i> , <i>Input Bias Current vs Temperature</i> , <i>Input Offset Current vs Temperature</i> , <i>Positive Output Voltage Swing vs Output Current</i> , <i>Negative Output Voltage Swing vs Output Current</i> , and <i>Small Signal</i> curves for CSO: FRE in the <i>Typical Characteristics</i>	9
• Updated the <i>Gain vs Frequency</i> curve for CSO: FRE in the <i>Typical Characteristics</i>	9
• Updated the <i>Positive Power Supply Rejection vs Frequency</i> curve for CSO: SHE in the <i>Typical Characteristics</i>	9
• Added CSO: SHE to <i>Small Signal</i> curves in the <i>Application Curves</i>	22
• Added CSO: FRE to <i>Large Signal</i> curves in the <i>Application Curves</i>	22
• Added <i>Large Signal</i> curves for CSO: SHE in the <i>Application Curves</i>	22
• Added <i>Small Signal</i> curves for CSO: FRE in the <i>Application Curves</i>	22
• Added part number flow information table to the <i>Device Nomenclature</i>	27

Changes from Revision B (May 2023) to Revision C (January 2026)	Page
• Added different fabrication process specifications for Input bias current in the <i>Features</i> section.....	1
• Added description of device flow information in the <i>Specifications</i>	4
• Added all chips site origins (CSO) condition to the typical test conditions in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Offset voltage (RTI) in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Power-supply rejection ratio (RTI) in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Long-term stability in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Common-mode rejection ratio in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Input bias current in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Input offset current in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Voltage noise (RTI) in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Current noise in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Gain error in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Gain drift in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Positive output voltage in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Negative output voltage in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Short-circuit current in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Bandwidth, –3dB in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Slew rate in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Settling time in the <i>Electrical Characteristics</i>	5
• Added all <i>chips site origins</i> (CSO) condition to the typical test conditions in the <i>Typical Characteristics</i>	9
• Added CSO: SHE to <i>Common-Mode Rejection vs Frequency, Settling Time vs Gain, Quiescent Current and Slew Rate vs Temperature, Input Overvoltage V/I Characteristics, Input Bias Current vs Temperature, Output Voltage Swing vs Power Supply Voltage, Short Circuit Output Current vs Temperature, Maximum Output Voltage vs Frequency, Total Harmonic Distortion + Noise vs Frequency, and Small-Signal Step Response</i> curves in the <i>Typical Characteristics</i>	9
• Added CSO: TID to <i>Gain vs Frequency, Positive Power Supply Rejection vs Frequency, Negative Power Supply Rejection vs Frequency, Input-Referred Voltage Noise vs Frequency, Positive Output Voltage Swing vs Output Current, Negative Output Voltage Swing vs Output Current, and Large-Signal Step Response</i> curves in the <i>Typical Characteristics</i>	9
• Added <i>Gain vs Frequency, Positive Power Supply Rejection vs Frequency, Negative Power Supply Rejection vs Frequency, Input-Referred Noise vs Frequency, Output Voltage Swing vs Output Current, and Large-Signal Step Response</i> curves for CSO: SHE in the <i>Typical Characteristics</i>	9
• Added <i>Common-Mode Rejection vs Frequency, Input-Referred Current Noise vs Frequency, Input Overvoltage V/I Characteristics, Input Bias Current vs Temperature, Input Offset Current vs Temperature, Maximum Output Voltage vs Frequency, Total Harmonic Distortion + Noise vs Frequency, and Small-Signal Step Response</i> curves for CSO: TID in the <i>Typical Characteristics</i>	9
• Added Part Number flow information table to the <i>Device Nomenclature</i>	21

Changes from Revision A (August 2023) to Revision B (January 2026)	Page
• Added description of device flow information in the <i>Specifications</i>	4
• Added different fabrication process specifications for Offset voltage (RTI) in the <i>Electrical Characteristics</i>	5
• Added all chips site origins (CSO) condition to the typical test conditions in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Offset voltage drift (RTI) in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Voltage noise (RTI) in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Current noise $f = 10\text{Hz}$ in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Current noise $f = 1\text{kHz}$ in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Output voltage in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Bandwidth, $-3\text{dB } G = 10\text{V/V}$ in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Slew rate in the <i>Electrical Characteristics</i>	5
• Added different fabrication process specifications for Quiescent current in the <i>Electrical Characteristics</i>	5
• Added <i>all chips site origins (CSO)</i> condition to the typical test conditions in the <i>Typical Characteristics</i>	8
• Added CSO: SHE to <i>Gain vs Frequency</i> , <i>Common-Mode Rejection vs Frequency</i> , <i>Positive Power Supply Rejection vs Frequency</i> , <i>Negative Power Supply Rejection vs Frequency</i> , <i>Input-Referred Noise vs Frequency</i> , <i>Output Voltage Swing vs Power Supply Voltage</i> , and <i>Short-circuit Output Current vs Temperature</i> curves in the <i>Typical Characteristics</i>	8
• Added CSO: TID to the <i>Quiescent Current and Slew Rate vs Temperature</i> , <i>Positive Output Voltage Swing vs Output Current</i> , <i>Negative Output Voltage Swing vs Output Current</i> , <i>Small-Signal Step Response</i> , and <i>Large-Signal Step Response</i> curves in the <i>Typical Characteristics</i>	8
• Added <i>Gain vs Frequency</i> , <i>Common-Mode Rejection vs Frequency</i> , <i>Positive Power Supply Rejection vs Frequency</i> , <i>Negative Power Supply Rejection vs Frequency</i> , and <i>Input-Referred Noise vs Frequency</i> curves for CSO: TID in the <i>Typical Characteristics</i>	8
• Added <i>Quiescent Current and Slew Rate vs Temperature</i> , <i>Output Voltage Swing vs Output Current</i> , <i>Small-Signal Step Response</i> and <i>Large-Signal Step Response</i> curves for CSO: SHE in the <i>Typical Characteristics</i>	8
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Changes from Revision B (April 2024) to Revision C (January 2026)	Page
• Added different fabrication process specifications for Bandwidth, –3dB to the <i>Description</i> section.....	1
• Added description of device flow information in the <i>Specifications</i>	3
• Added different fabrication process specifications for Offset voltage in the <i>Electrical Characteristics</i>	4
• Added all chips site origins (CSO) condition to the typical test conditions in the <i>Electrical Characteristics</i>	4
• Added different fabrication process specifications for Offset voltage drift in the <i>Electrical Characteristics</i>	4
• Added different fabrication process specifications for Common-mode voltage rejection in the <i>Electrical Characteristics</i>	4
• Added different fabrication process specifications for Common-mode input impedance in the <i>Electrical Characteristics</i>	4
• Added different fabrication process specifications for Gain nonlinearity in the <i>Electrical Characteristics</i>	4
• Added different fabrication process specifications for Output voltage in the <i>Electrical Characteristics</i>	4
• Added different fabrication process specifications for Load capacitance in the <i>Electrical Characteristics</i>	4
• Added different fabrication process specifications for Short-circuit current in the <i>Electrical Characteristics</i>	4
• Added different fabrication process specifications for Bandwidth, –3dB in the <i>Electrical Characteristics</i>	4
• Added different fabrication process specifications for Full power bandwidth in the <i>Electrical Characteristics</i> ..	4
• Added different fabrication process specifications for Slew rate in the <i>Electrical Characteristics</i>	4
• Added different fabrication process specifications for Quiescent current in the <i>Electrical Characteristics</i>	4
• Added typical test conditions in the <i>Typical Characteristics</i>	6
• Added all <i>chips site origins (CSO)</i> condition to the typical test conditions in the <i>Typical Characteristics</i>	6
• Added CSO: SHE to <i>Common-mode Rejection vs Frequency, Power-supply Rejection vs Frequency, Positive Common-mode Voltage Range vs Positive Power-supply Voltage, Negative Common-mode Voltage Range vs Negative Power-supply Voltage, Small Signal Step Response, and Large Signal Step Response</i> curves in the <i>Typical Characteristics</i>	6
• Added <i>Common-mode Rejection vs Frequency, Positive Power-supply Rejection vs Frequency, Negative Power-supply Rejection vs Frequency, Common-mode Voltage Range vs Power-supply Voltage, Small Signal Step Response, Small Signal Step Response vs Capacitive Load, and Large Signal Step Response</i> curves for CSO: TID in the <i>Typical Characteristics</i>	6
• Added Part Number flow information table to the <i>Device Nomenclature</i>	19

The datasheet number will be changing.

Device Family	Change From:	Change To:
INA12x	SBOS051F	SBOS051G
INA2128	SBOS035B	SBOS035C
INA141	SBOS052A	SBOS052B
INA117	SBOS154B	SBOS154C

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/INA128>

<http://www.ti.com/product/INA129>

<http://www.ti.com/product/INA2128>

<http://www.ti.com/product/INA141>

<http://www.ti.com/product/INA117>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact.

Changes to product identification resulting from this PCN:

None.

Product Affected:

INA128U/2K51G4	INA128UA	INA128U-2/2K5	INA129U/2K5G4.B
INA129U/2K5	INA128UA.B	INA128UA/2K5.B	INA128P
INA128U	INA129P.A	INA129U/2K5.B	INA128PA.A
INA129PA.A	INA129UA	INA129UA.B	INA129U.B
INA129UA/2K5.B	INA128PG4	INA128P.A	INA129UA/2K5
INA128PA	INA128U.B	INA128U/2K5.B	INA128U/2K51G4.B
INA128U-2/2K5.B	INA128UA/2K5	INA129PA	INA129U
INA128U/2K5	INA129P	INA129U/2K5G4	INA2128U.B
INA2128UA	INA2128UA/1K	INA2128U/1K.B	INA2128U1G4
INA2128UA.B	INA2128U/1K	INA2128UA/1K.B	INA2128U1G4.B
INA2128UAG4.B	INA2128UAG4	INA2128U	INA141U
INA141U/2K5	INA141U.B	INA141U/2K5.B	INA141UA/2K5
INA141UA.B	INA141UA/2K5.B	INA141UA	INA117KU
INA117KU.B	INA117KU/2K5	INA117KU/2K5.B	INA117P
INA117P.B	INA117AM	INA117AM.A	INA117BM
INA117BM.A	INA117SM	INA117SM.A	INA117SMQ
INA117SMQ.A			

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